

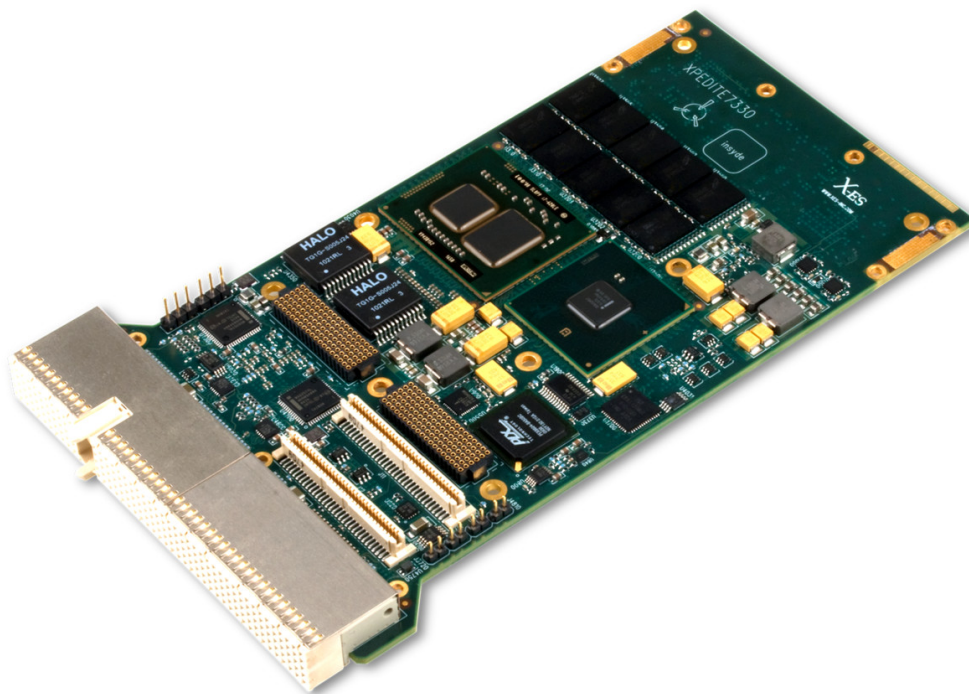
XPedite7330

**Not Recommended
for New Designs**

Intel® Core™ i7 Processor-Based Conduction- or Air-Cooled 3U CompactPCI Module

Please see XPedite7530

- ▶ Intel® Core™ i7-610E, -620LE, -620UE, and -660UE processors
- ▶ Dual-core with Hyper-Threading Technology
- ▶ 3U CompactPCI module
- ▶ Conduction or air cooling
- ▶ Up to 4 GB of DDR3-1066 ECC SDRAM in two channels
- ▶ 32 MB of NOR boot flash
- ▶ Up to 16 GB of NAND flash
- ▶ Configurable as system controller or peripheral
- ▶ Hosts a PrPMC or XMC
- ▶ Two 10/100/1000BASE-T Ethernet ports out J2
- ▶ Two RS-232/422/485 serial ports out J2
- ▶ Wind River VxWorks BSP
- ▶ Linux BSP
- ▶ Microsoft Windows drivers
- ▶ Contact factory for availability of GHS INTEGRITY BSP, QNX Neutrino BSP, and LinuxWorks LynxOS BSP



XPedite7330

The XPedite7330 is a conduction- or air-cooled, 3U CompactPCI (cPCI), single board computer based on the Intel® Core™ i7 processor and Intel® QM57 chipset. With dual cores operating at 2.53, 2.0, 1.06, or 1.33 GHz, the Intel® Core™ i7 delivers enhanced performance and efficiency for today's network information processing and other embedded computing applications.

Complementing processor performance, the XPedite7330 features up to 4 GB of DDR3-1066 ECC SDRAM, XMC/PrPMC support, and up to 16 GB of NAND flash. Two Gigabit Ethernet ports are routed to J2 for additional system flexibility.

The XPedite7330 provides a high-performance, feature-rich solution for current and future generations of embedded applications. Operating system support for Wind River VxWorks, QNX Neutrino, Linux Board Support Packages (BSPs) is available, as well as Microsoft Windows drivers.

X-ES

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Extreme Engineering Solutions

3225 Deming Way, Suite 120 • Middleton, WI 53562

Phone: 608.833.1155 • Fax: 608.827.6171

sales@xes-inc.com • <http://www.xes-inc.com>

Processor

- Intel® Core™ i7 processor operating at 2.53, 2.0, 1.06, or 1.33 GHz
- Dual-core with Hyper-Threading Technology
- Intel® QM57 chipset
- Dual-channel integrated memory controller
- Integrated graphics controller
- 4 MB of shared cache

Memory

- Up to 4 GB of DDR3-1066 ECC SDRAM in two channels
- 32 MB of NOR boot flash
- Up to 16 GB of NAND flash

J1 cPCI Interface

- 32-bit PCI interface operating at 33 or 66 MHz
- System controller-capable with onboard clocking and arbitration
- Peripheral slot-capable

J2 cPCI Interface

- Two 10/100/1000BASE-T Ethernet ports
- Two RS-232/422/485 serial ports
- Four GPIO signals
- Four SATA ports capable of 3 Gb/s
- Two USB 2.0 ports
- One DVI port

XMC/PrPMC Site

- 32-bit, 33 MHz PCI bus (PMC interface)
- x8 PCIe port (XMC interface)

Software Support

- Wind River VxWorks BSP
- Linux BSP
- Microsoft Windows drivers
- GHS INTEGRITY BSP (contact factory)
- QNX Neutrino BSP (contact factory)
- LynuxWorks LynxOS BSP (contact factory)

Physical Characteristics

- Conduction- or air-cooled 3U CompactPCI form factor
- Dimensions: 100 mm x 160 mm

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements

- Power will vary based on configuration and usage. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C ambient
Vibration	0.002 g ² /Hz, 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

